

**FOR ADDITIONAL INFORMATION  
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**FOR IMMEDIATE RELEASE**

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# Press Release

## **An ECTC Special Presentation by Dr. Wusheng Yin *An Overview of Advanced Materials***



(Albany, NY) **May 7, 2015** We at YINCAE Advanced Materials, LLC would like to cordially invite you to a special presentation, *An Overview of Advanced Materials* by Dr. Wusheng Yin; our President. YINCAE develops and manufactures a wide range of materials including:

- ❖ Solder Joint Encapsulants
- ❖ Underfill Materials
- ❖ Die Attach Adhesives
- ❖ Conformal Coatings
- ❖ Nano Composite Formulations
- ❖ Wafer Level Materials
- ❖ Optoelectronic Material
- ❖ Thermal Interface Material

YINCAE offers a variety Adhesives, Thermal Interface, and Chip/ Board/ Packaging level materials for any level of necessity. Dr. Yin created the WORLD's FIRST Lead -Free Solder Joint Encapsulation Adhesive solutions for wafer level, flip chip, POP, LGA, BGA and many more. YINCAE offers SJEAs for low, medium, and high temperature solder alloy applications with differential chemistry and electrical/ thermal conductivity for your individualized needs.

**Date:** Wednesday, May 27 2015

**Time:** 1:00pm-3:00 pm

**Location:** Sheraton Hotel (4<sup>th</sup> Floor- Rooms 411/415) on-site of the ECTC 2015 Conference.

For more information or if you have any questions please feel free to contact the Administrative Office: [www.yincae.com](http://www.yincae.com) or 518-452-2880. We look forward to seeing you there.

